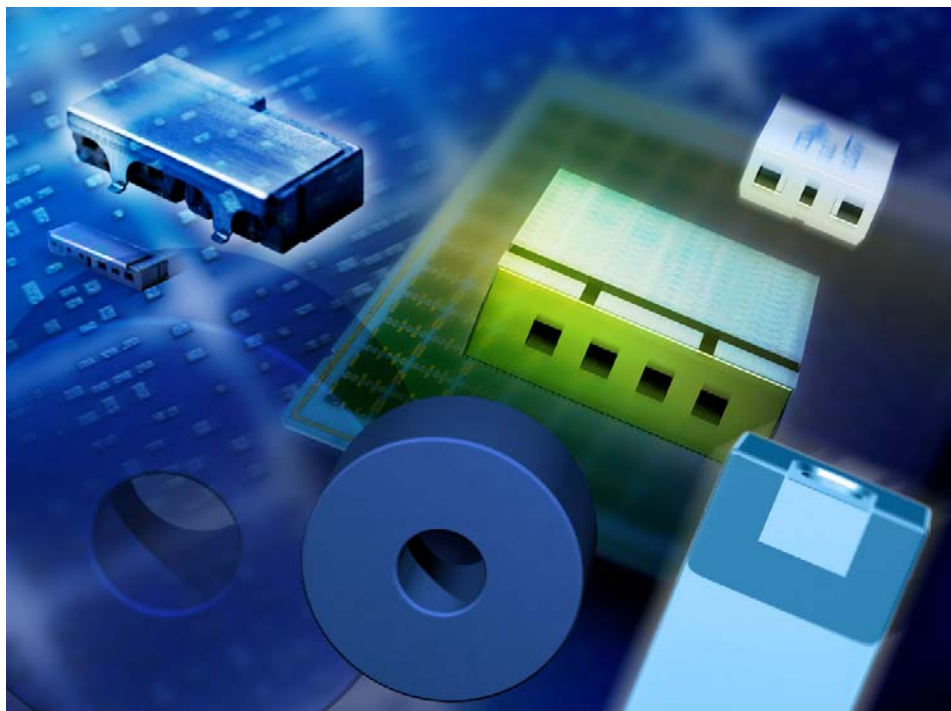


Data Sheet

Features

- SMD filter consisting of coupled resonators with stepped impedances
- MgTiO_3 - CaTiO_3 ($\epsilon_r = 21$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper ($10\mu\text{m}$) and tin ($>5\mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

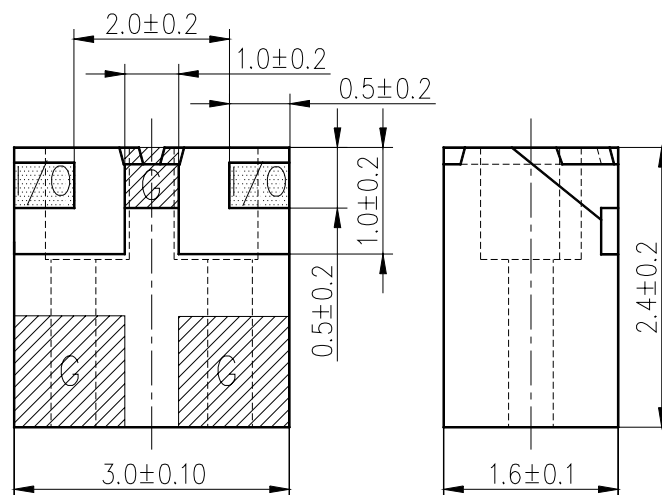
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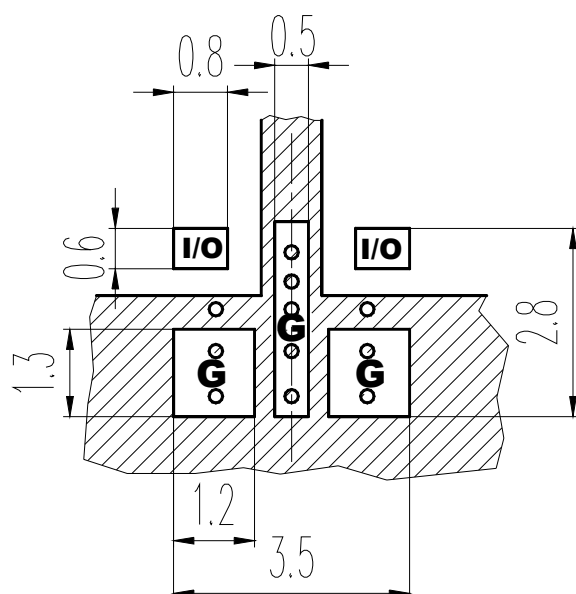
Data Sheet

Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint



□ soldering area
via diameter 0.3mm

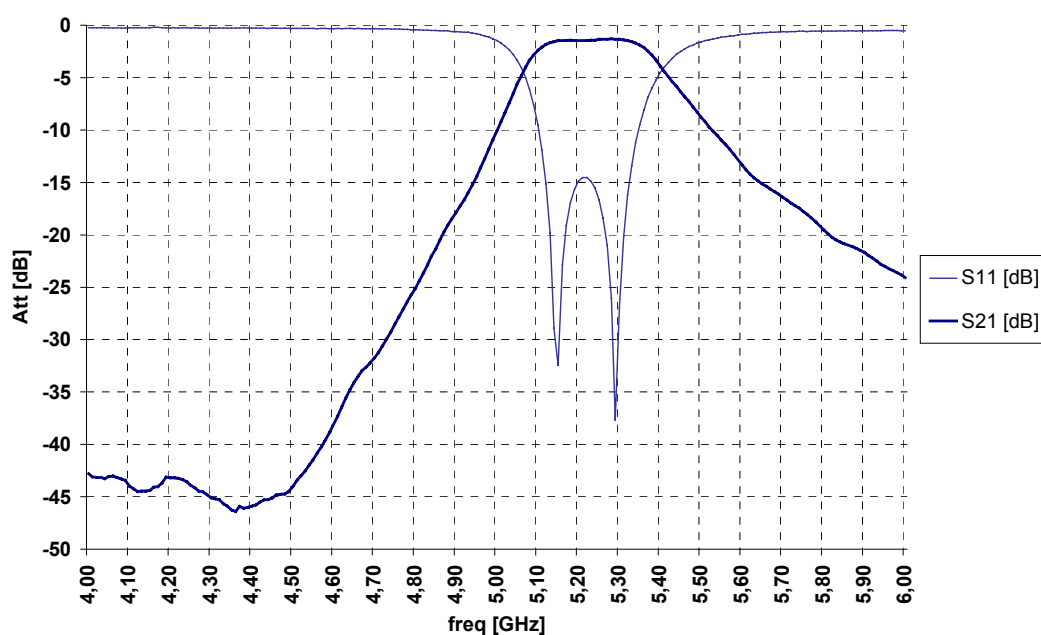
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Data Sheet
Characteristics

		min.	typ.	max.	
Center frequency	f_C	-	5250	-	MHz
Insertion loss	α_{IL}		1.4	1.8	dB
Passband	B	200			MHz
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Power	P			1.0	W
Attenuation	α				
	at DC to 1990 MHz	55	60		dB
	at 1990 to 2170 MHz	53	58		dB
	at 2400 to 2500 MHz	50	55		dB
	at 4500 MHz	35	40		dB
	at 5000 MHz	10			dB
	at 5500 MHz	7			dB
	at 6.5 to 10 GHz	20	25		dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	-40 / + 85	°C

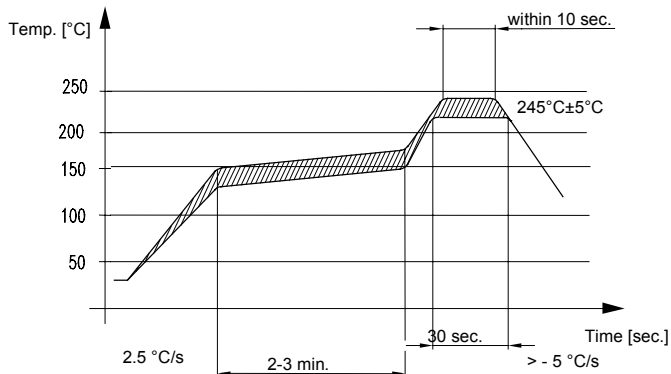
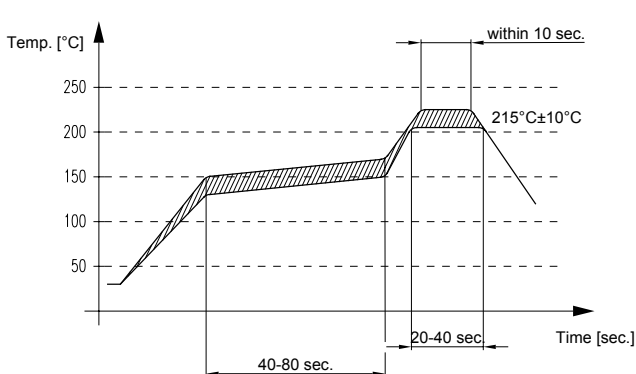
Typical passband characteristic


Processing information

- ## Soldering Requirements

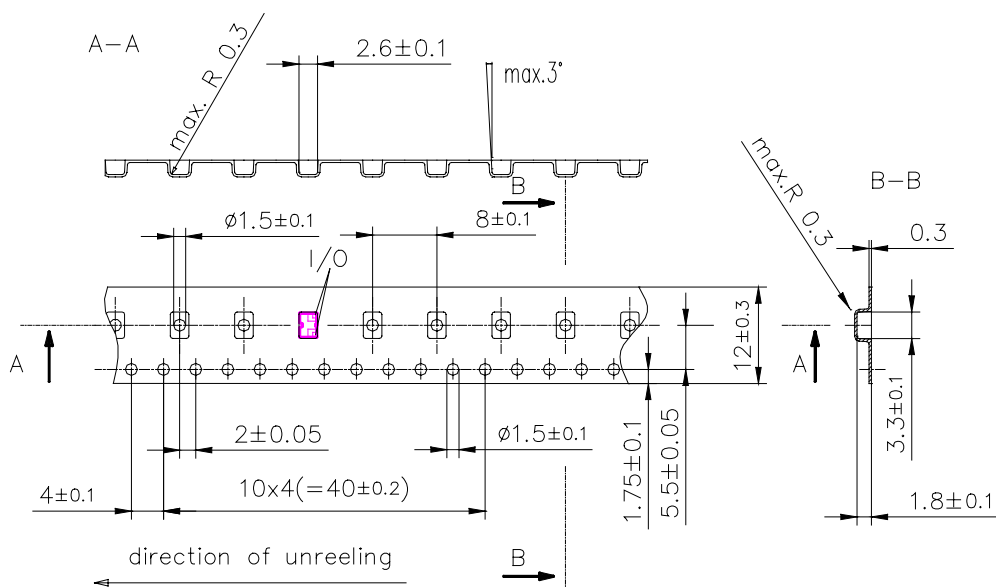
	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature	235 (max. 2 sec.)	260 (max. 2 sec.)	°C
(measuring point on top surface of the component)	225 (max. 10 sec.)	250 (max. 10 sec.)	°C

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 4000



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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